



DESCRIPTION

The AM6512 is available in DFN8(5x6) package.

ORDERING INFORMATION

Package Type	Part Number	
DFN8 (5x6)	J8	AM6512J8R
		AM6512J8VR
Note	V: Halogen free Package R: Tape & Reel SPQ: 3,000pcs/ Reel	
AiT provides all RoHS products Suffix " V " means Halogen free Package		

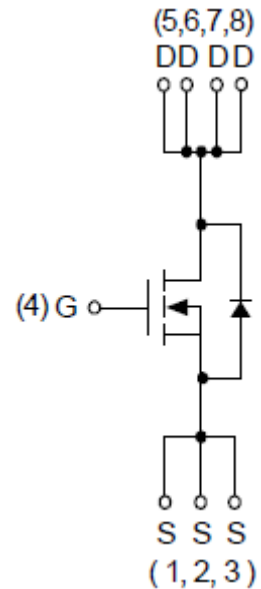
FEATURES

- 30V/100A,
 $R_{DS(ON)} = 1.7m\Omega$ (max.) @ $V_{GS} = 10V$
 $R_{DS(ON)} = 2.6m\Omega$ (max.) @ $V_{GS} = 4.5V$
- Reliable and Rugged
- 100% UIS Tested
- Available in DFN8(5x6) package.

APPLICATION

- Power Management in Notebook Computer or DC/DC Converters.
- Vcore Switching for Server
- Oring and Load Switch

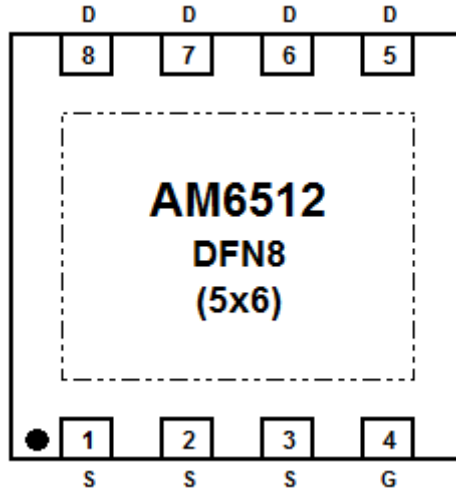
PIN DESCRIPTION



N-Channel MOSFET



PIN DESCRIPTION



Top View

Pin #	Symbol	Function
1	S	Source
2	S	Source
3	S	Source
4	G	Gate
5	D	Drain
6	D	Drain
7	D	Drain
8	D	Drain



ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$, unless Otherwise Noted

V_{DSS} , Drain-Source Voltage		30V
V_{GSS} , Gate-Source Voltage		$\pm 20\text{V}$
T_J , Maximum Junction Temperature		150°C
T_{STG} , Storage Temperature Range		$-55^\circ\text{C} \sim 150^\circ\text{C}$
I_S , Diode Continuous Forward Current	$T_C = 25^\circ\text{C}$	100A ^{NOTE1}
I_D , Continuous Drain Current	$T_C = 25^\circ\text{C}$	100A ^{NOTE1}
	$T_C = 100^\circ\text{C}$	100A ^{NOTE1}
I_{DM} , Pulsed Drain Current	$T_C = 25^\circ\text{C}$	400A ^{NOTE2}
P_D , Maximum Power Dissipation	$T_C = 25^\circ\text{C}$	104W
	$T_C = 100^\circ\text{C}$	41W
$R_{\theta JC}$, Thermal Resistance-Junction to Case	Steady State	1.2°C/W
I_{DM} , Pulsed Drain Current	$T_A = 25^\circ\text{C}$	100A
	$T_A = 70^\circ\text{C}$	25A
I_D , Continuous Drain Current	$T_A = 25^\circ\text{C}$	25A
	$T_A = 70^\circ\text{C}$	20A
P_D , Maximum Power Dissipation	$T_A = 25^\circ\text{C}$	2.3W
	$T_A = 70^\circ\text{C}$	1.5W
$R_{\theta JA}$, Thermal Resistance-Junction to Ambient	$t \leq 10\text{s}$	17°C/W
	Steady State	55°C/W
I_{AS} ^{NOTE3} , Avalanche Current, Single Pulse	$L = 0.5\text{mH}$	42A
E_{AS} ^{NOTE3} , Avalanche Energy, Single Pulse	$L = 0.5\text{mH}$	440mJ

Stress beyond above listed "Absolute Maximum Ratings" may lead permanent damage to the device. These are stress ratings only and operations of the device at these or any other conditions beyond those indicated in the operational sections of the specifications are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

NOTE1: Package is limited to 100A.

NOTE2: Pulse width limited by max. junction temperature.

NOTE3: UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature $T_J = 25^\circ\text{C}$).



ELECTRICAL CHARACTERISTICS

T_A = 25°C, unless Otherwise Noted

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _{DS} =-250μA	30	-	-	V
Drain-Source Breakdown Voltage (transient)	BV _{DSSst}	V _{GS} =0V, I _{D(aval)} =35A T _{case} =25°C, t _{transient} =100ns	34	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =24V, V _{GS} =0V	-	-	1	μA
		T _J =85°C	-	-	30	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _{DS} =250μA	1.3	1.8	2.5	V
Gate Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
Drain-Source On-state Resistance	R _{DS(ON)} NOTE4	V _{GS} =10V, I _{DS} =40A	-	1.35	1.7	mΩ
		T _J =125°C	-	2	-	
		V _{GS} =4.5V, I _{DS} =20A	-	2	2.6	
Forward Transconductance	G _{fs}	V _{DS} =5V, I _{DS} =20A	-	55	-	S
Diode Characteristics						
Diode Forward Voltage	V _{SD} NOTE4	I _{SD} =20A, V _{GS} =0V	-	0.77	1.1	V
Reverse Recovery Time	t _{rr}	I _F =20A, dI _{SD} /dt=100A/μs V _{DD} =15V	-	37	-	ns
Charge Time	t _a		-	21	-	
Discharge Time	t _b		-	16	-	
Reverse Recovery Charge	Q _{rr}		-	31	-	
Dynamic Characteristics NOTE5						
Gate Resistance	R _G	V _{GS} =0V, V _{DS} =0V, F=1MHz	0.7	1.0	1.8	Ω
Input Capacitance	C _{iss}	V _{GS} =0V, V _{DS} =15V, Frequency=1.0MHz	3600	4500	5400	pF
Output Capacitance	C _{oss}		840	940	1050	
Reverse Transfer Capacitance	C _{rss}		330	430	530	
Turn-on Delay Time	t _{d(ON)}	V _{DD} =15V, R _L =15Ω, I _{DS} =1A, V _{GEN} =10V, R _G =1Ω	-	19	23	ns
Turn-on Rise Time	t _r		-	10	13	
Turn-off Delay Time	t _{d(OFF)}		-	56	67	
Turn-off Fall Time	t _f		-	34	40	
Gate Charge Characteristics NOTE5						
Total Gate Charge	Q _g	V _{DS} =15V, V _{GS} =4.5V, I _{DS} =40A	-	36	43	nC
Total Gate Charge	Q _g	V _{DS} =15V, V _{GS} =10V, I _{DS} =40A	-	78	93	
Threshold Gate Charge	Q _{gth}		-	2.8	3.3	
Gate-Source Charge	Q _{gs}		-	6.3	7.5	
Gate-Drain Charge	Q _{gd}		-	21	27	

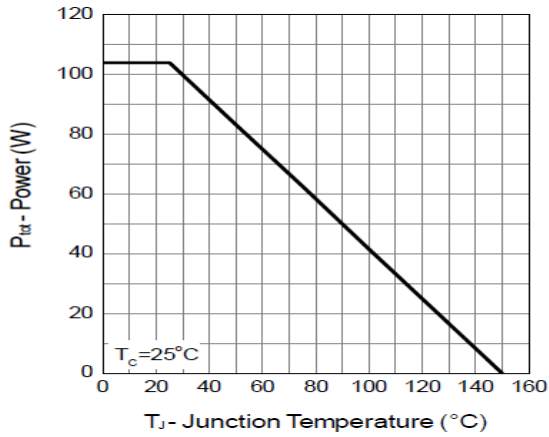
NOTE4: Pulse test; pulse width≤300us, duty cycle≤2%

NOTE5: Guaranteed by design, not subject to production testing.

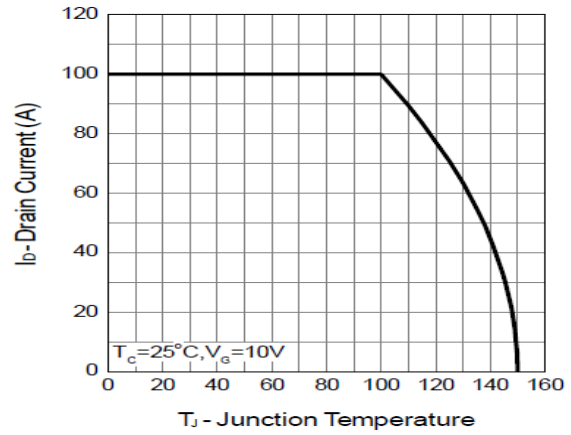


TYPICAL PERFORMANCE CHARACTERISTICS

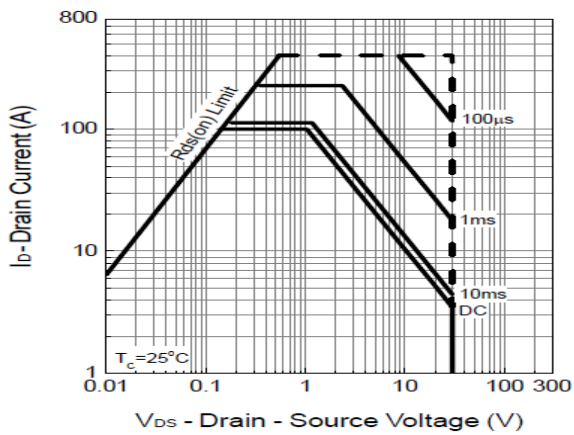
1. Power Dissipation



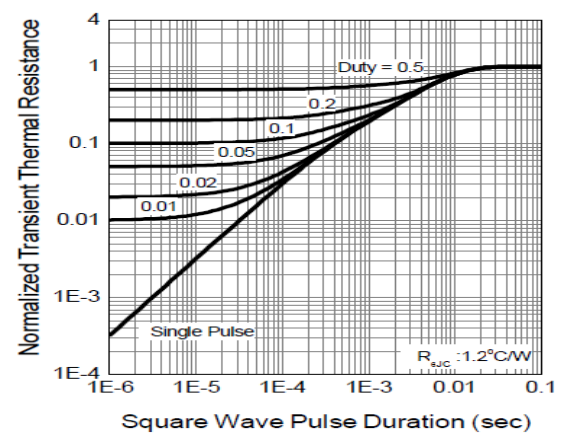
2. Drain Current



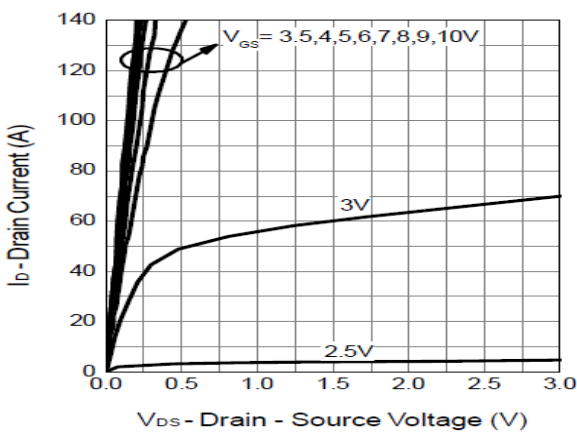
3. Safe Operation Area



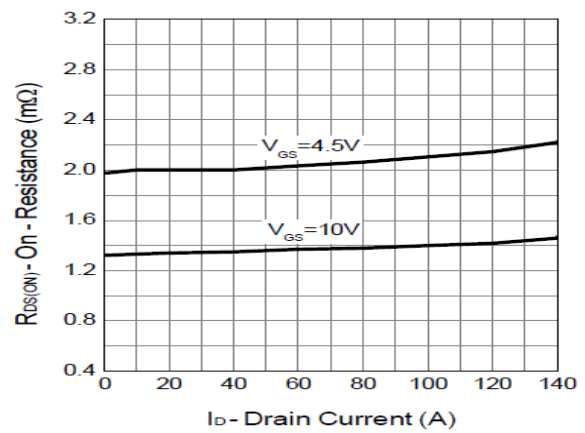
4. Thermal Transient Impedance



5. Output Characteristics

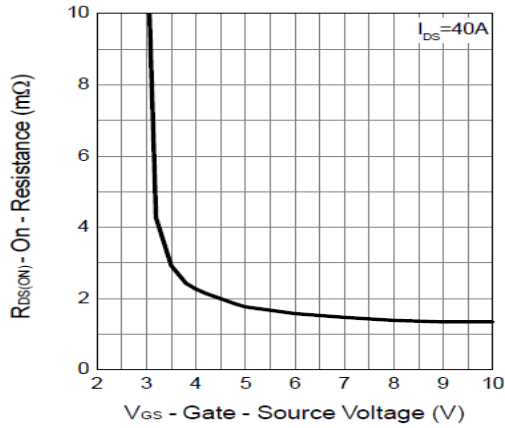


6. Drain-Source On Resistance

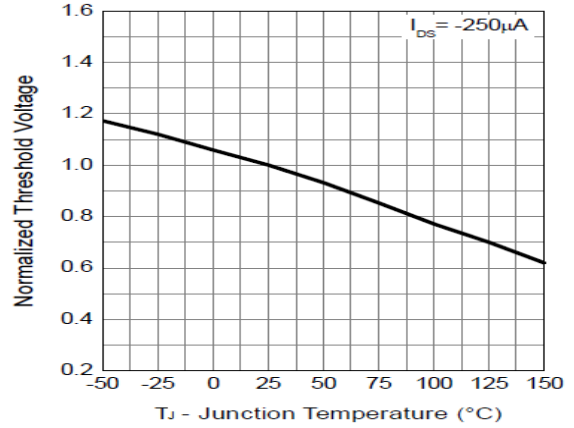




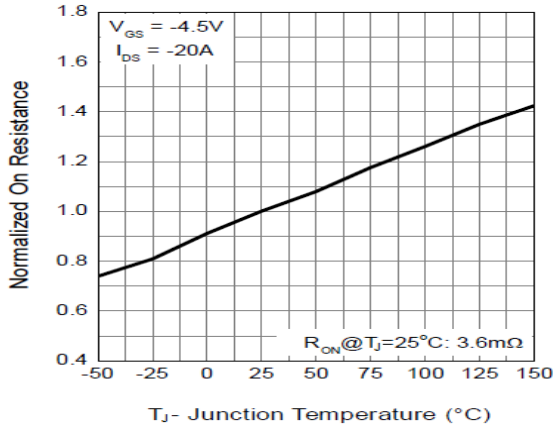
7. Gate-Source On Resistance



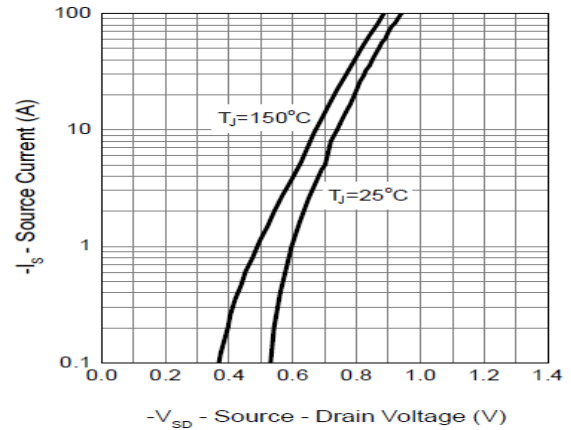
8. Gate Threshold Voltage



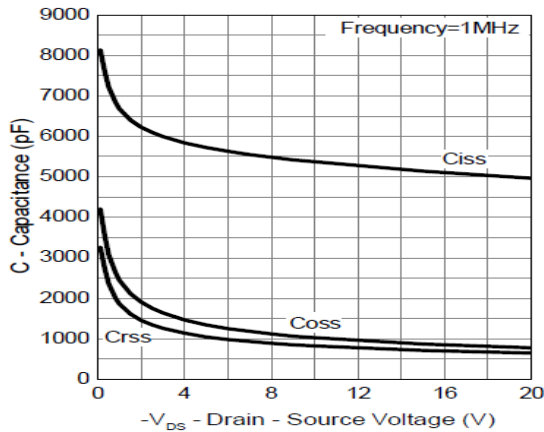
9. Drain-Source On Resistance



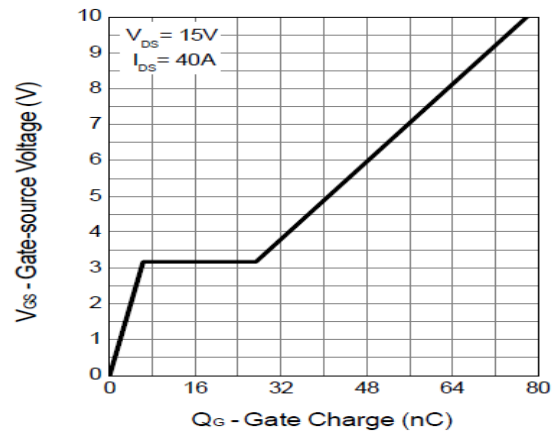
10. Source-Drain Diode Forward



11. Capacitance

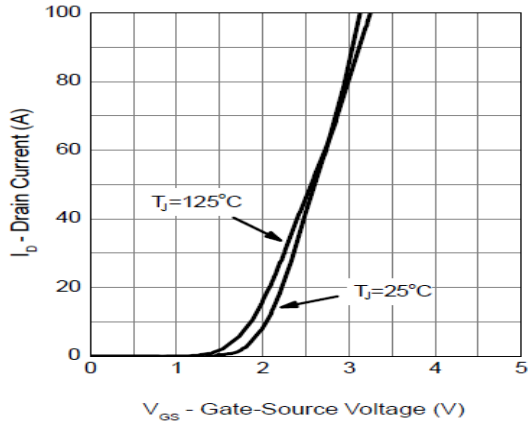


12. Gate Charge



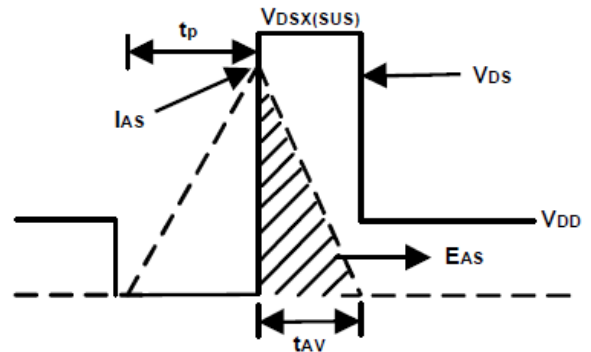
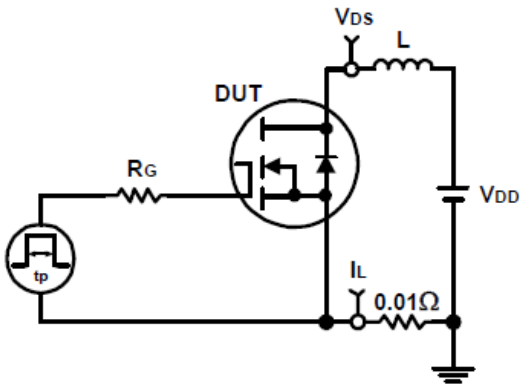


13. Transfer Characteristics

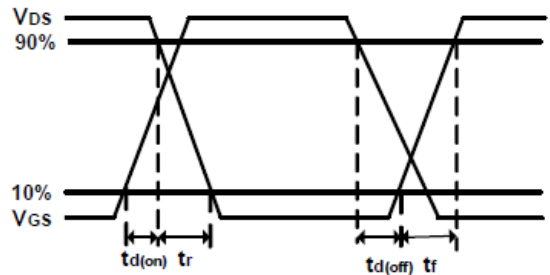
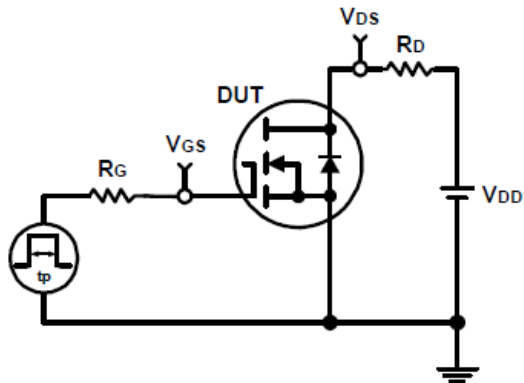


DETAILED INFORMATION

Avalanche Test Circuit and Waveforms



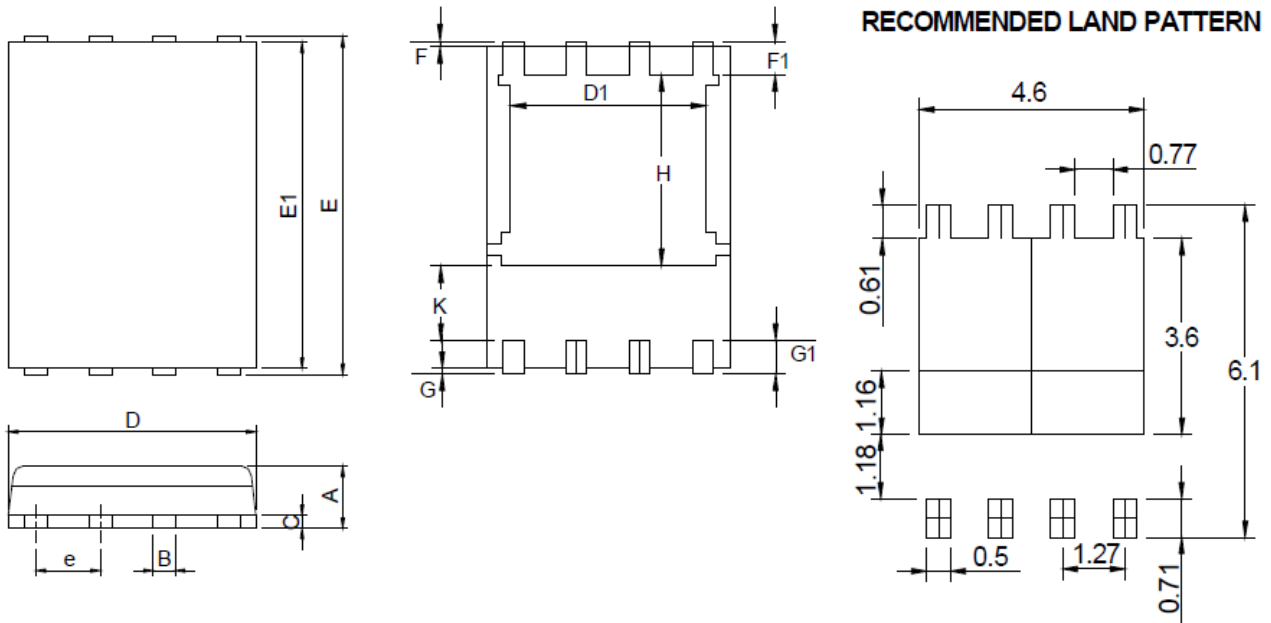
Switching Time Test Circuit and Waveforms





PACKAGE INFORMATION

Dimension in DFN8 (Unit: mm)



Symbol	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	0.90	1.20	0.035	0.047
B	0.3	0.51	0.012	0.020
C	0.19	0.25	0.007	0.010
D	4.80	5.30	0.189	0.209
D1	4.00	4.40	0.157	0.173
E	5.90	6.20	0.232	0.244
E1	5.50	5.80	0.217	0.228
e	1.27 BSC		0.050 BSC	
F	0.05	0.30	0.002	0.012
F1	0.35	0.75	0.014	0.030
G	0.05	0.30	0.002	0.012
G1	0.35	0.75	0.014	0.030
H	3.34	3.9	0.131	0.154
K	0.762	-	0.03	-



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